

1/1 - (C) FILE CAPLUS  
 AN - 1992:491548 CAPLUS XP-002215885  
 DN - 117:91548  
 TI - Injection-moldable epoxy resin compositions  
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 SO - Jpn. Kokai Tokkyo Koho, 6 pp.  
 CODEN: JKXXAF  
 DT - Patent  
 LA - Japanese  
 IC - ICM C08G059/18  
 ICS C08K007/22;C08L63/00  
 CC - 37-6 (Plastics Manufacture and Processing)  
 Section cross-reference(s): 38

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PN	JP4059820	A	19920226	JP 1990-172234	19900629 <--
AB	<p><u>Epoxy compds. (100 parts) consisting of .gtoreq.65 wt.% liq. epoxy with low viscosity and .ltoreq.35 wt.% reactive diluents with 1-3 ep groups are mixed with 1-30 parts expandable microcapsules with av. c (in the unexpanded state) .ltoreq.100 .mu.m and with curing agents t</u>  <u>-ve the title compns., which may also contain 5-50 parts filler and are useful, e.g., for auto parts. The microcapsules have walls of acrylonitrile-vinylidene chloride copolymer or acrylonitrile-Me acry copolymer (I) and are filled with low-b.p. compds. [Thus, 80 parts bisphenol A-based epoxy resin (viscosity 13,000 cP, epoxy equiv. wt. 20 parts 1,6-hexanediol diglycidyl ether, 5 parts microcapsules (av. -m. 15 .mu.m, with I enclosing isobutane), and 0.5 part other additives mixed at 40.degree. and 10 kg/cm2; the mixt. obtained (106 parts) wa cured with 24 parts modified alicyclic polyamine (viscosity 30 cP, a H equiv. wt. 42) at 150.degree. for 5 min and injection-molded to gi products with flexural strength 20.0 kg/cm2, flexural modulus 710 kg and smoothness .+- .5.0 .mu.m.</u></p>				
ST	epoxy molding expandable microcapsule				
IT	Epoxy resins, miscellaneous. RL: MSC (Miscellaneous) (injection-moldable compns. of, contg. expandable microcapsules)				
IT	Molding of plastics and rubbers (injection, of epoxy resins contg. expandable microcapsules, for products with dimensional stability and smoothness)				
IT	Capsules (micro-, expandable, contg. low-b.p. compds., injection-moldable e resin compns. contg., for products with dimensional stability and smoothness)				
IT	92183-42-1, Bisphenol F-epichlorohydrin copolymer			143019-21-0	
	RL: USES (Uses) (injection-moldable compns. for, contg. expandable microcapsules)				
IT	75-28-5, Isobutane				
	RL: USES (Uses) (injection-moldable epoxy resin compns. contg. microencapsulated)				
IT	9010-76-8, Acrylonitrile-vinylidene chloride copolymer			24968-79-4,	
	Acrylonitrilemethyl acrylate copolymer RL: USES (Uses) (microcapsules, expandable, enclosing low-b.p. compds., injection-moldable epoxy resin compns. contg.)				

*Inventive step of claims 1-*